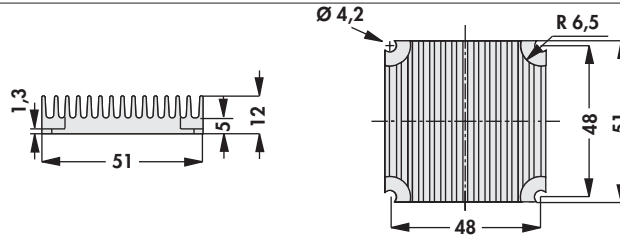


A

B



art. no.

 R_{th} [K/W]

suitable for processor type

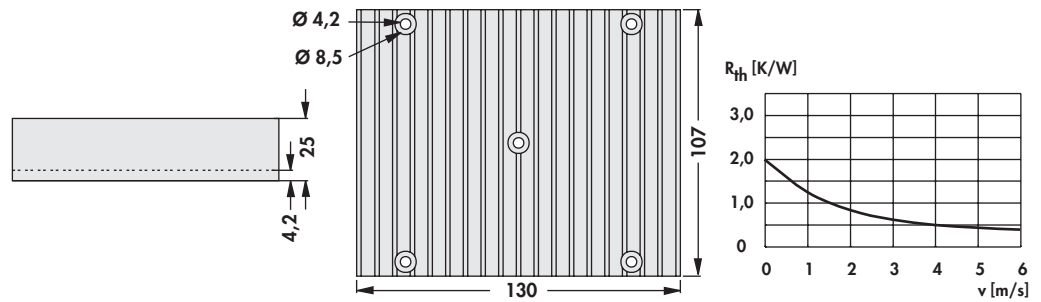
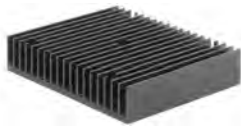
ICK PPC 51

8.1

Power PC

C

D



art. no.

 R_{th} [K/W]

suitable for processor type

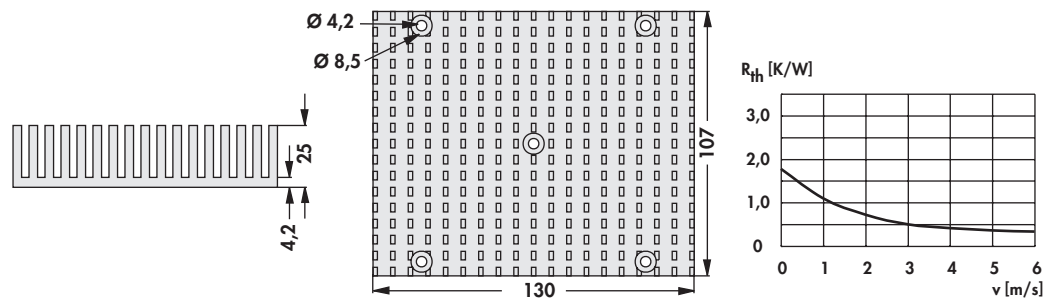
ICK PEN 3 XE

2

Intel® Pentium® III-Xeon™ Slot II Format

E

F



art. no.

 R_{th} [K/W]

suitable for processor type

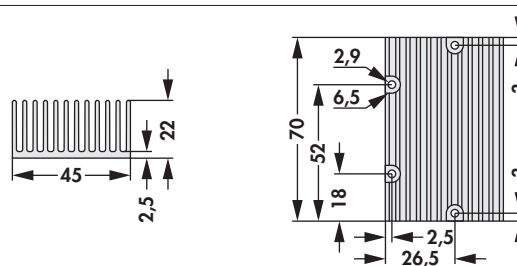
ICK PEN 3 XE 1

1.8

Intel® Pentium® III-Xeon™ Slot II Format

G

H

Heatsink specially for Q7 "Embedded-Boards"


art. no.

 R_{th} [K/W]

suitable for processor type

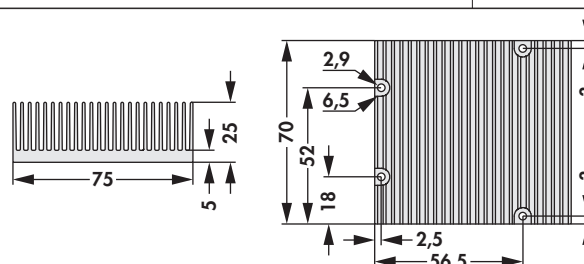
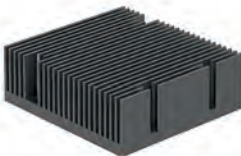
ICK EM 22

4.4

MQ7 Board

I

K



art. no.

 R_{th} [K/W]

suitable for processor type

ICK EM 25

3.9

Q7 Board


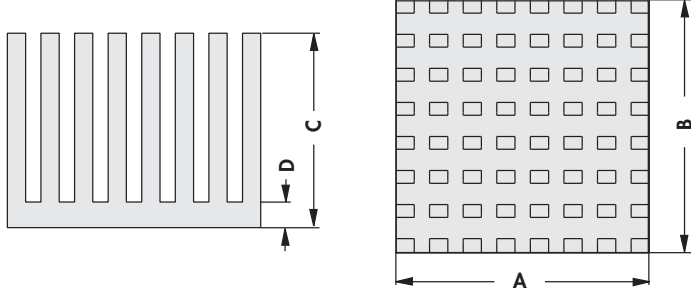
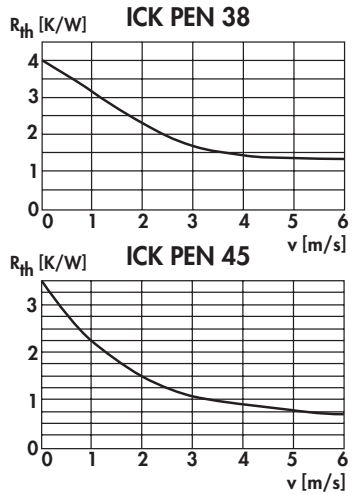

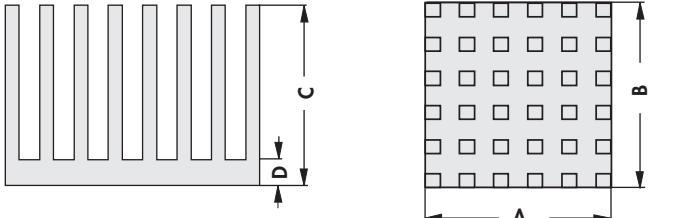
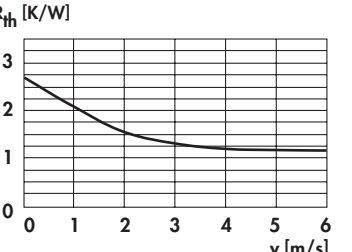
L

M


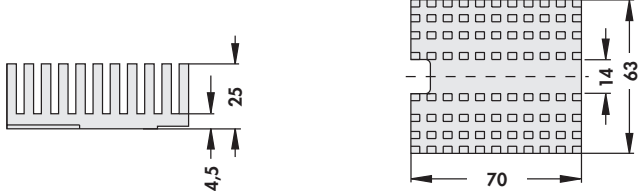
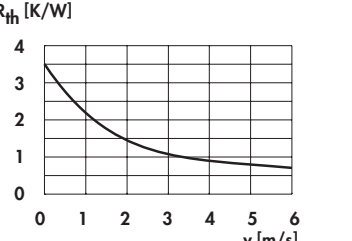


N

– customer specific versions and modifications on request

						
art. no.	R_{th} [K/W]	suitable for processor type	dim. [mm]			
ICK PEN 38 F	4.0	AMD® K6-III/ IDT W2A/ MMX/ IDT C6/ Intel® Pentium®/ AMD® K6-2	A	B	C	D
ICK PEN 38 W			49.5	49.5	38	5.0
ICK PEN 45 W	3.5		50.0	50.0	45	3.5
						
art. no.	R_{th} [K/W]	suitable for processor type	dim. [mm]			
ICK PRO 40 W	2.7	Intel® Pentium® PRO	65	67.5	40	4.5

F = with double-sided thermally conductive adhesive foil
W = for thermally conductive adhesive (please order separately)
WLK ... → E 72

		
art. no.	R_{th} [K/W]	suitable for processor type
ICK PEN 3 FC	3.5	Intel® Pentium® III FC PGA (Mendocino, Coppermine)

fixing method: K = with fixing clamp (incl. one-sided adherent thermal foil)